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Should be replaced with:

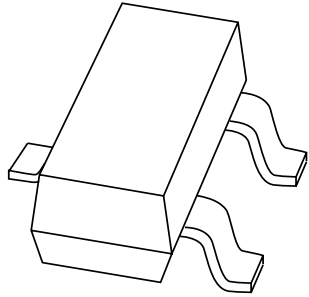
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via [salesaddresses@nexperia.com](mailto:salesaddresses@nexperia.com)). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# DATA SHEET



## **BAL99** High-speed diode

Product data sheet  
Supersedes data of 1999 May 26

2003 Dec 12

# High-speed diode

# BAL99

## FEATURES

- Small plastic SMD package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 70 V
- Repetitive peak reverse voltage: max. 70 V
- Repetitive peak forward current: max. 500 mA.

## APPLICATIONS

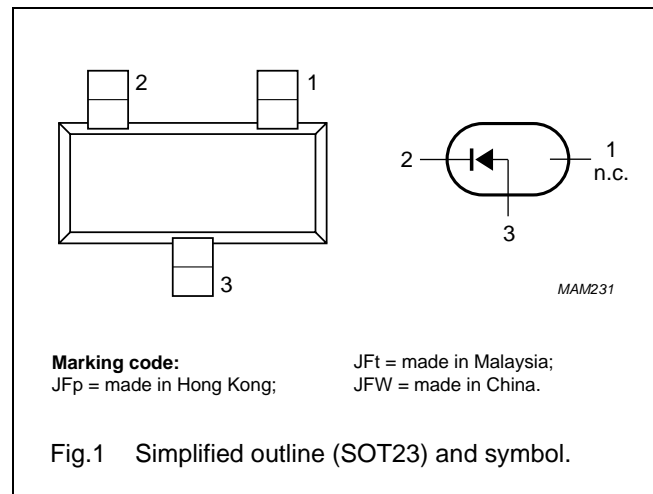
- High-speed switching in e.g. surface mounted circuits.

## DESCRIPTION

The BAL99 is a high-speed switching diode fabricated in planar technology, and encapsulated in the small SOT23 plastic SMD package.

## PINNING

PIN	DESCRIPTION
1	not connected
2	cathode
3	anode



## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAL99	-	plastic surface mounted package; 3 leads	SOT23

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{RRM}$	repetitive peak reverse voltage		-	70	V
$V_R$	continuous reverse voltage		-	70	V
$I_F$	continuous forward current	see Fig.2; note 1	-	215	mA
$I_{FRM}$	repetitive peak forward current		-	500	mA
$I_{FSM}$	non-repetitive peak forward current	square wave; $T_j = 25\text{ °C}$ prior to surge; see Fig.4 $t_p = 1\ \mu\text{s}$ $t_p = 1\ \text{ms}$ $t_p = 1\ \text{s}$	-	4 1 0.5	A A A
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ °C}$ ; note 1	-	250	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C

## Note

1. Device mounted on an FR4 printed-circuit board.

## High-speed diode

BAL99

**ELECTRICAL CHARACTERISTICS** $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
$V_F$	forward voltage	see Fig.3		
		$I_F = 1\text{ mA}$	715	mV
		$I_F = 10\text{ mA}$	855	mV
		$I_F = 50\text{ mA}$	1	V
		$I_F = 150\text{ mA}$	1.25	V
$I_R$	reverse current	see Fig.5		
		$V_R = 25\text{ V}$	30	nA
		$V_R = 70\text{ V}$	1	$\mu\text{A}$
		$V_R = 25\text{ V}; T_j = 150\text{ }^\circ\text{C}$	30	$\mu\text{A}$
		$V_R = 70\text{ V}; T_j = 150\text{ }^\circ\text{C};$	50	$\mu\text{A}$
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 0;$ see Fig.6	1.5	pF
$t_{rr}$	reverse recovery time	when switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA};$ $R_L = 100\ \Omega;$ measured at $I_R = 1\text{ mA};$ see Fig.7	4	ns
$V_{fr}$	forward recovery voltage	when switched from $I_F = 10\text{ mA}; t_r = 20\text{ ns};$ see Fig.8	1.75	V

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-tp)}$	thermal resistance from junction to tie-point		360	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

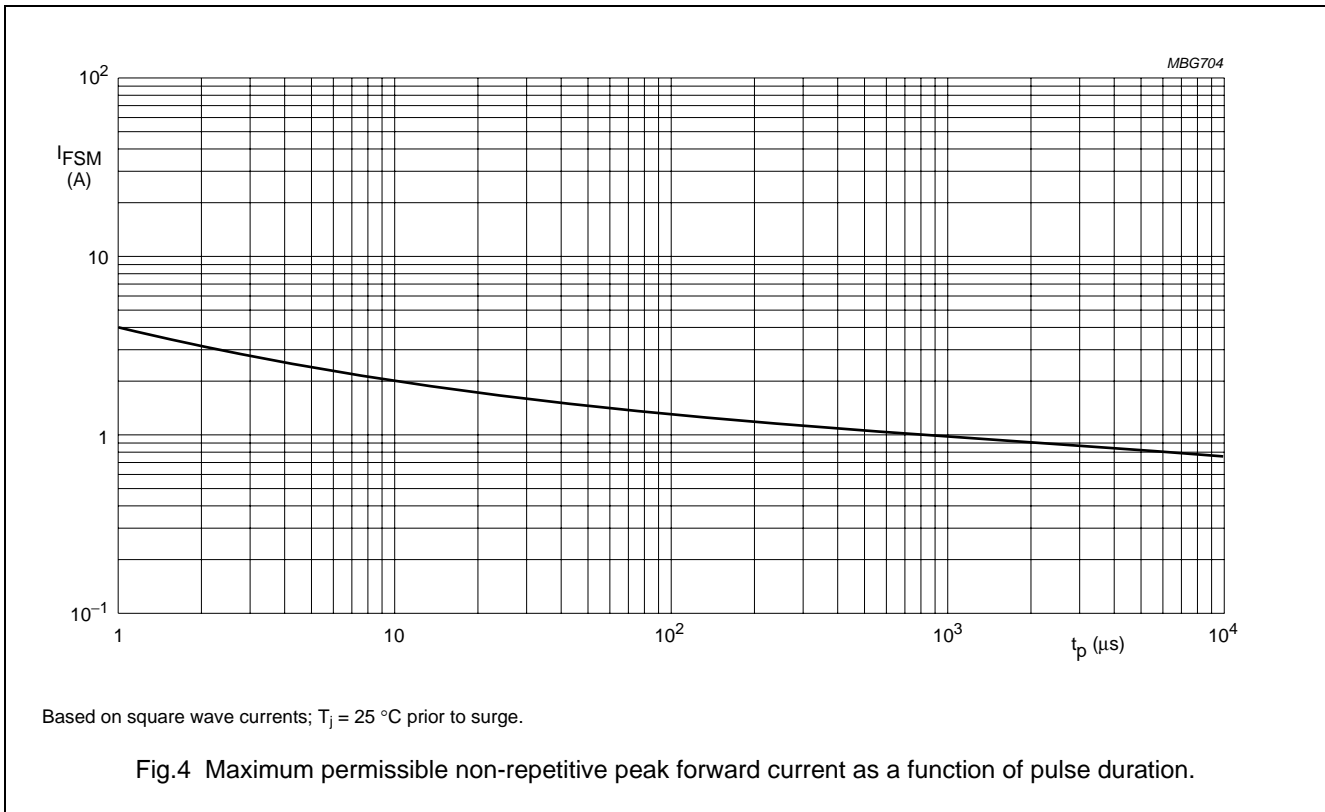
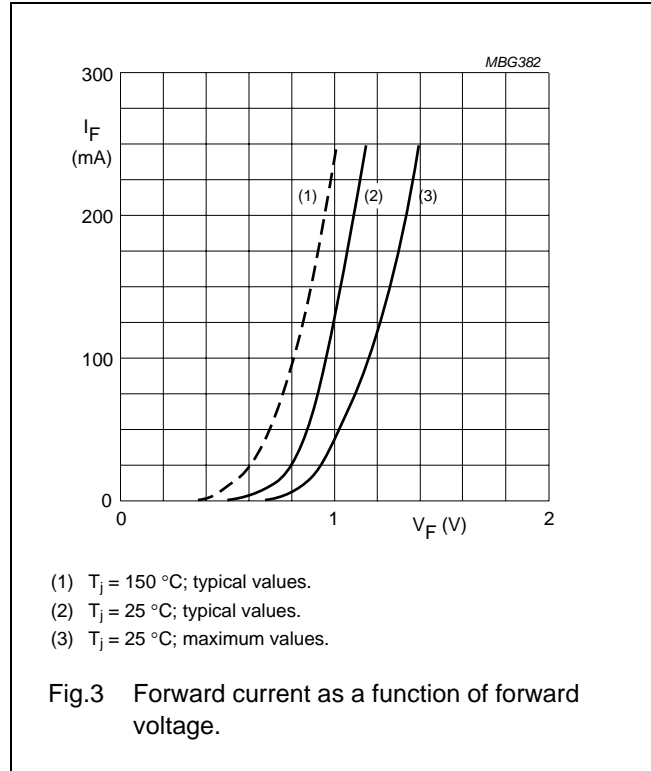
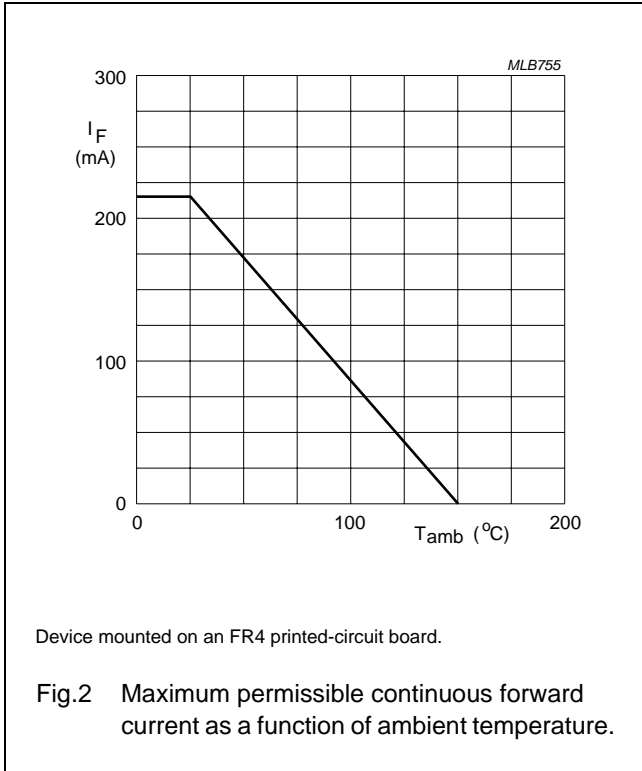
**Note**

- Device mounted on an FR4 printed-circuit board.

# High-speed diode

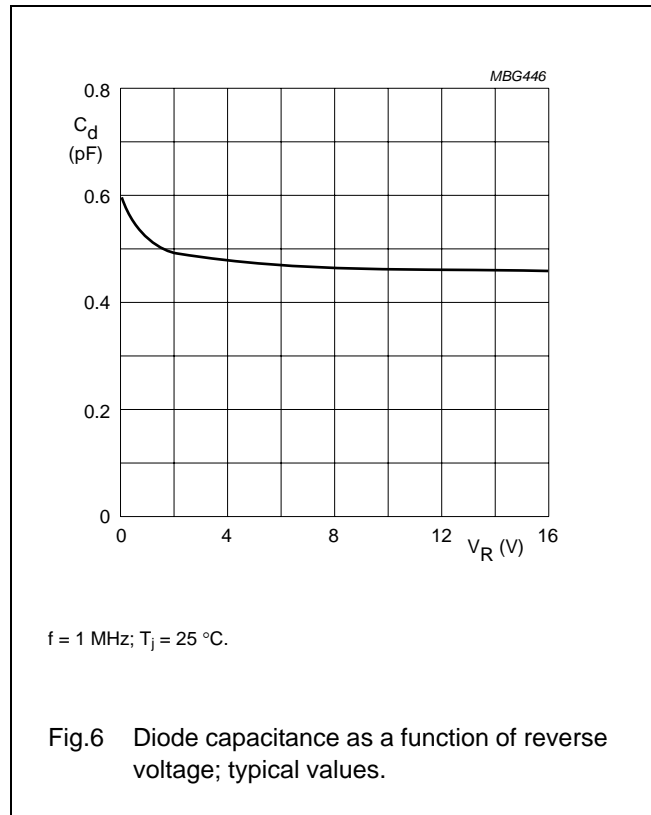
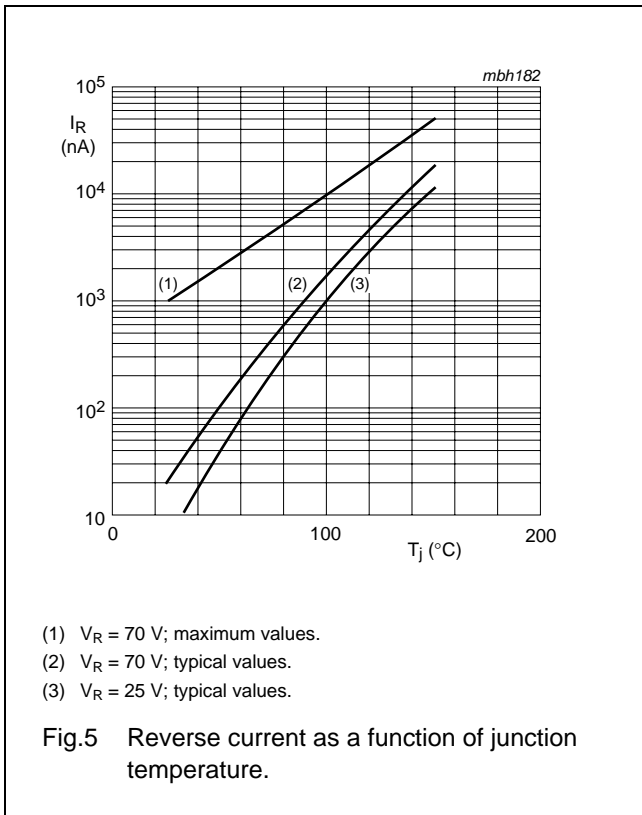
# BAL99

## GRAPHICAL DATA



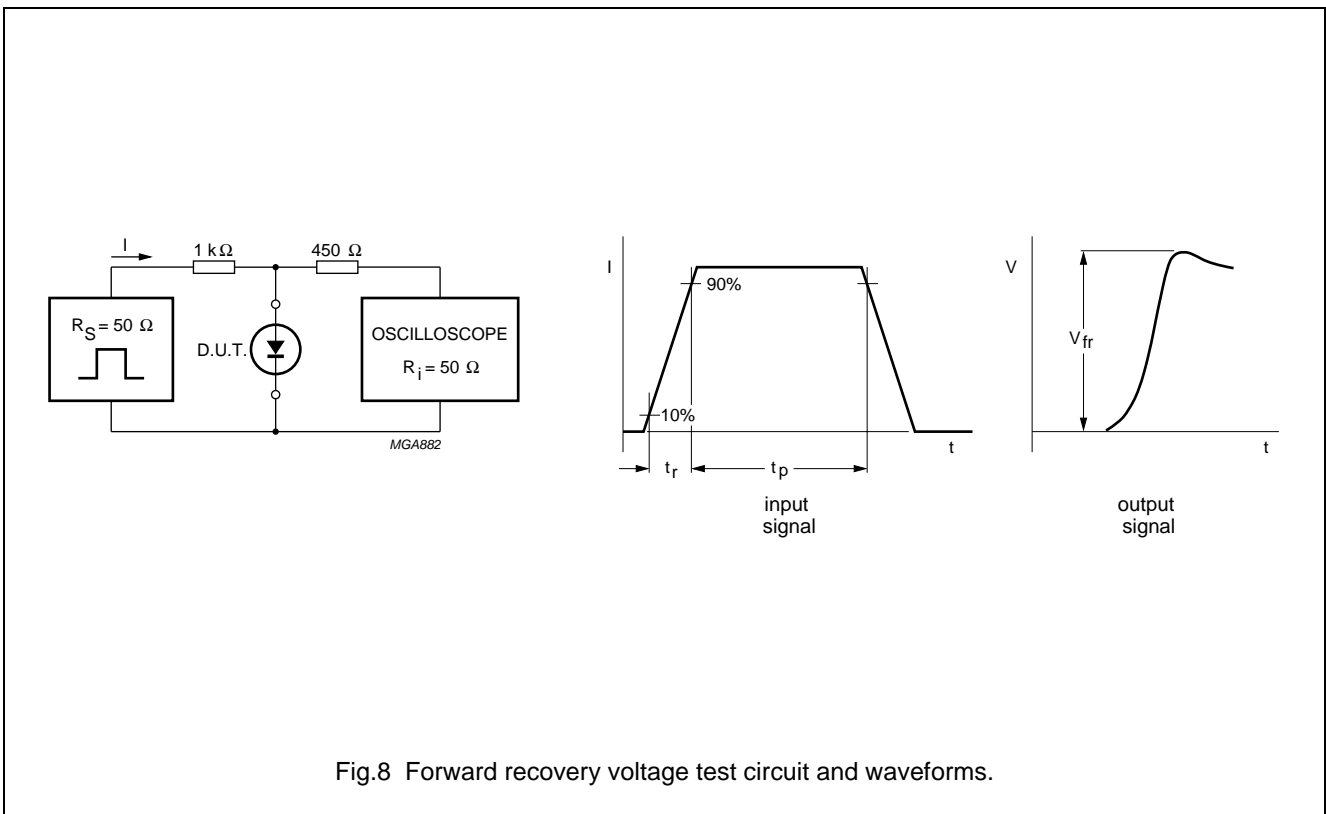
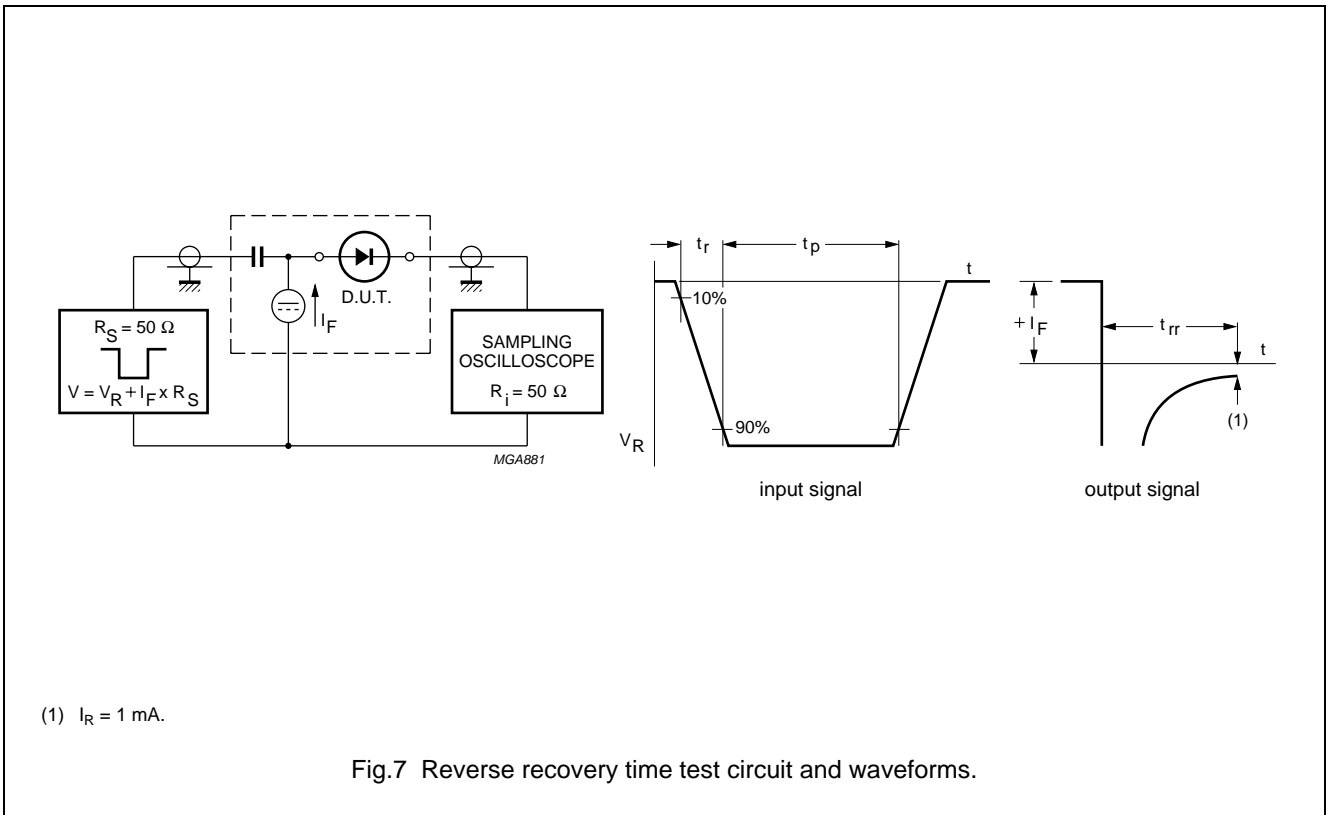
High-speed diode

BAL99



High-speed diode

BAL99



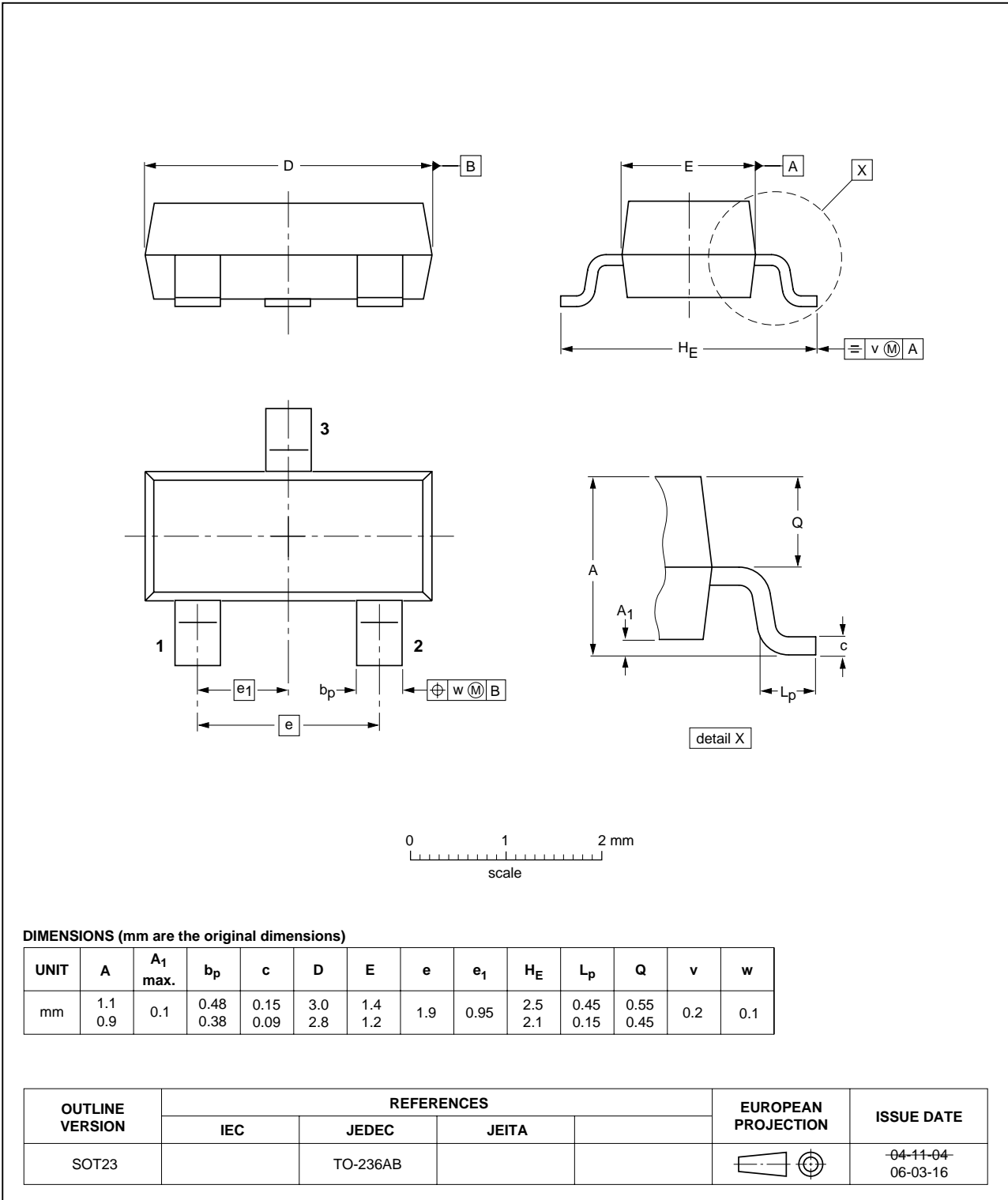
# High-speed diode

BAL99

## PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23





# High-speed diode

BAL99

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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# ***NXP Semiconductors***

## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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